



100% Material Declaration Data Sheet for 7 Series FBG900

PK546 (v1.1) November 2, 2012

Average Weight: 3.7865g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.296758	7.837
	Silicon (Si)	7440-21-3	100.00	Basis	0.296758	
Solder Bump					0.019309	0.510
	Tin (Sn)	7440-31-5	63.00		0.012165	
	Lead (Pb)	7439-92-1	37.00		0.007144	
Solder Paste					0.071000	1.875
	Tin (Sn)	7440-31-5	96.50	Basis	0.068515	
	Silver (Ag)	7440-22-4	3.00	Basis	0.002130	
	Copper (Cu)	7440-50-8	0.50	Basis	0.000355	
Capacitor 1					0.011700	0.309
	BaTiO3 type	12047-27-7	70.60	Ceramic	0.008260	
	Nickel (Ni)	7440-02-0	6.70	Inner electrode	0.000784	
	Copper (Cu)	7440-50-8	20.10	Outer electrode	0.002352	
	Nickel (Ni)	7440-02-0	0.80	Plating 1	0.000094	
	Tin (Sn)	7440-31-5	1.80	Plating 2	0.000211	
Capacitor 2					0.009200	0.243
	BaTiO3 type	12047-27-7	51.10	Ceramic	0.004701	
	Copper (Cu)	7440-50-8	27.00	Inner electrode	0.002484	
	Nickel (Ni)	7440-02-0	16.90	Outer electrode	0.001555	
	Nickel (Ni)	7440-02-0	2.00	Plating 1	0.000184	
	Tin (Sn)	7440-31-5	3.00	Plating 2	0.000276	
Capacitor 3					0.002400	0.063
	BaTiO3 type	12047-27-7	66.00	Ceramic	0.001584	
	Nickel (Ni)	7440-02-0	2.67	Inner electrode	0.000064	
	Copper (Cu)	7440-50-8	23.33	Outer electrode	0.000560	
	Nickel (Ni)	7440-02-0	2.33	Plating 1	0.000056	
	Tin (Sn)	7440-31-5	5.67	Plating 2	0.000136	

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Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Underfill					0.053000	1.400
	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	20.00	Basis	0.010600	
	Phenolic Resin	Trade Secret	15.00	Basis	0.007950	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00	Basis	0.002650	
	Amine type accelerator	Trade Secret	5.00	Basis	0.002650	
	Silicon Dioxide	60676-86-0	51.50	Basis	0.027295	
	Carbon Black	1333-86-4	1.00	Basis	0.000530	
	Additives	Trade Secret	2.50	Additive	0.001325	
Solder Ball					0.751829	19.855
	Tin (Sn)	7440-31-5	96.50	Main Material	0.725515	
	Silver (Ag)	7440-22-4	3.00	Main Material	0.022555	
	Copper (Cu)	7440-50-8	0.50	Main Material	0.003759	
Substrate					2.571305	67.908
	Copper (Cu)	7440-50-8	37.42		0.962228	
	Tin (Sn)	7440-31-5	0.92		0.023579	
	Lead (Pb)	7439-92-1	0.19		0.004937	
	Silver (Ag)	7440-22-4	0.02		0.000463	
	BT Core	N/A	48.05		1.235150	
	ABF	N/A	10.92		0.280665	
	Solder Mask	N/A	2.51		0.064283	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/23/2012	1.0	Initial Xilinx release.
11/02/2012	1.1	Update substrate component.

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